

4

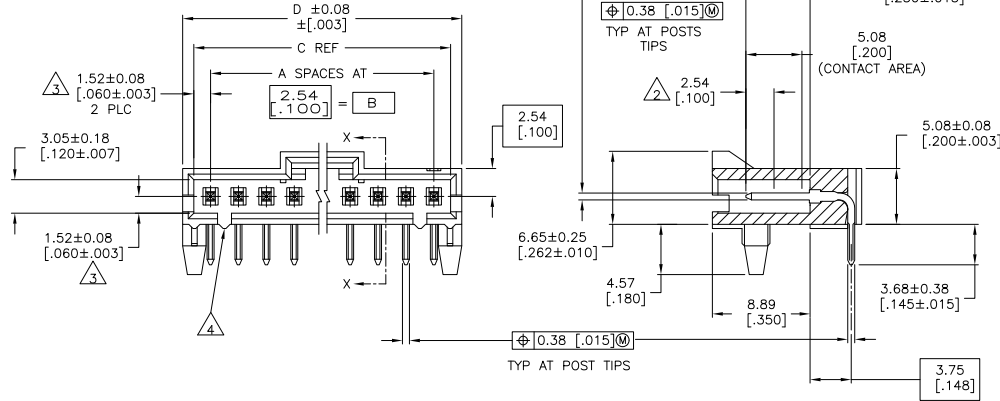
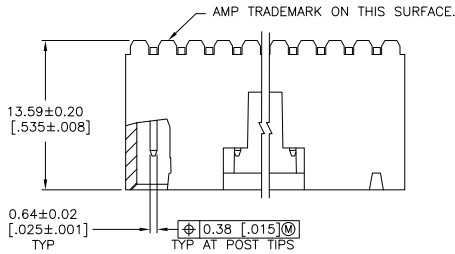
3

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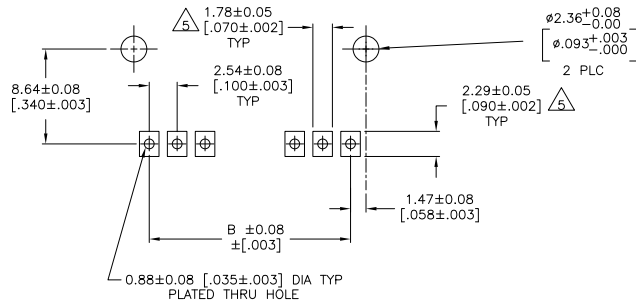
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LOC	DIST	REVISIONS			
F	LNK	DESCRIPTION	DATE	BY	APPD
P2		REVISED PER ECO-11-004587	11MAR11	RK	HMR



- 1 0.000381 [.000015] GOLD IN THE CONTACT AREA, 0.00254-0.00508 [.000100-.000200] MATTE TIN-LEAD ON THE SOLDER TAIL, ALL OVER 0.00127 [.000050] NICKEL.
- 2 POINT OF MEASUREMENT FOR PLATING THICKNESS
- 3 THE NOTED DIMENSIONS APPLY FROM THE BASIC DIMENSION LINE (NOT THE POST CENTERLINE) TO THE SURFACE INDICATED
- 4 ON ASSEMBLIES WITH FOUR OR MORE POSITIONS, TWO POLARIZATION SLOTS. ON ASSEMBLIES WITH TWO OR THREE POSITIONS, ONE POLARIZATION SLOT.
- 5 DIMENSIONS NOTED ARE FOR SOLDER STENCIL LAYOUT FOR USE WITH A 1.57±0.20 [.062±.008] THICK PRINTED CIRCUIT BOARD
- 6 PARTS ARE PACKAGED IN GANG OF TUBES
- 7 0.000381 [.000015] GOLD IN THE CONTACT AREA, 0.00254-0.00508 [.000100-.000200] MATTE TIN ON THE SOLDER TAIL, ALL OVER 0.00127 [.000050] NICKEL.
- 8 OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



SECTION X-X

SEE SHEET 2 FOR PART NUMBER TABLE

RECOMMENDED PC BOARD MOUNTING DIMENSIONS
 RECOMMENDED STENCIL THICKNESS = 0.25 [.010]

THIS DRAWING IS A CONTROLLED DOCUMENT.		DRN	C. DOUTY	2-22-88
		CHK	T. C. CLARK	2-22-88
		APPD	T. C. CLARK	2-22-88
		PRODUCT SPEC		
		APPLICATION SPEC		
		WEIGHT		
		CUSTOMER DRAWING		
		SCALE	4:1	
		SHEET	1 of 2	
		REV	P2	

TE Connectivity

HEADER ASSY, AMPMODU MTE, RIGHT
 ANGLE, SINGLE ROW, .100
 POSTS, WITH LATCH & HOLD DOWNS

SIZE ONE CODE DRAWING NO. RESTRICTED TO
 A2 00779 C=104361

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